

**BONDING +  
SEALING +  
ENCAPSULATION**

**Kisling**



# 8792 + 8992

**The two-component polyurethane gap filler with low hardness and adhesion for typical battery cell technology applications.**

Our innovative filler matrix also provide the ideal basis for demanding heat-conducting pastes. These are characterised by high thermal conductivity and simultaneous outstanding workability, and are thus serious contributors to optimal thermal management. At the same time, they offer high levels of electrical insulation while not relying to any extent on silicones or solvents.

8792 + 8992 is a polyurethane-based, two-component gap filler. After application, the GapFiller remains its stability and exhibits low adhesion after curing, which means that the component can be removed from the part again. The gap filler also has a low shore hardness and is therefore soft and flexible. Ideal area of applications are power electronics (e.g. printed circuit boards) or battery cell technology.

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- + 1:1 Mixing ratio
- + Gap filling
- + Excellent thermal conductivity of 2W/mK
- + Silicone-free
- + Low adhesion strength



## Specifications

<b>Product category</b>	Encapsulants   Gap Filler
<b>Chemical base</b>	Polyurethane
<b>Color</b>	Natural (Beige)
<b>Density [g/cm<sup>3</sup>]</b>	2.40 – 2.50
<b>Mixing ratio [by weight]</b>	100 : 100
<b>Viscosity [mPas]</b>	75 000 – 95 000
<b>Pot life [min]</b>	20 – 30
<b>Shore hardness (DIN EN ISO 868)(DIN EN ISO 868)</b>	A40 – 50
<b>Temperature range [°C]</b>	-40 – +130
<b>Curing conditions</b>	Cold curing
<b>Thermal conductivity [W/mK]</b>	2.0
<b>Glass transition temperature [°C]</b>	-62
<b>CTE &lt; T<sub>g</sub> [ppm/K]</b>	29,6
<b>CTE &gt; T<sub>g</sub> [ppm/K]</b>	183,4
<b>UL94</b>	V0, 4,0mm